

### Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- An automotive-compliant part is available under separate datasheet (<u>DFLS1150Q</u>)

### **Mechanical Data**

- Package: PowerDI<sup>®</sup>123
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.01 grams (Approximate)

#### PowerDI123



Top View

# Ordering Information (Note 4)

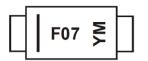
| Part Number   | Packaga    | Packing |             |  |
|---------------|------------|---------|-------------|--|
| Fait Nulliber | Package    | Qty.    | Carrier     |  |
| DFLS1150-7    | PowerDI123 | 3,000   | Tape & Reel |  |
| DFLS1150-13   | PowerDI123 | 10,000  | Tape & Reel |  |

EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

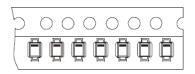
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# Marking Information



F07 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: K = 2023) M = Month (ex: 9 = September)



#### Date Code Key

Notes:

| Year  | 2005 | -   | 2023 | 2024 | 2025 | 2026 | 2027 | 2028 | 2029 | 2030 | 2031 | 2032 |
|-------|------|-----|------|------|------|------|------|------|------|------|------|------|
| Code  | S    | -   | K    | L    | М    | Ν    | Р    | R    | S    | Т    | U    | V    |
|       |      |     |      |      |      |      |      |      |      |      |      |      |
| Month | Jan  | Feb | Mar  | Apr  | Мау  | Jun  | Jul  | Aug  | Sep  | Oct  | Nov  | Dec  |



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

| Characteristic  | Symbol             | Value | Unit |
|---|--------------------|-------|------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage              | Vrrm<br>Vrwm<br>Vr | 150   | V    |
| RMS Reverse Voltage   | VR(RMS)            | 106   | V    |
| Average Forward Current   | lf(AV)             | 1.0   | A    |
| Non-Repetitive Peak Forward Surge Current 8.3ms<br>Single Half Sine Wave Superimposed on Rated Load | IFSM               | 50    | A    |

### **Thermal Characteristics**

| Characteristic   | Symbol           | Тур    | Max  | Unit |
|--|------------------|--------|------|------|
| Thermal Resistance Junction to Soldering Point (Note 5)              | Rejs             | —      | 7    | °C/W |
| Thermal Resistance Junction to Ambient (Note 6) $T_A = +25^{\circ}C$ | R <sub>0JA</sub> | 125    | —    | °C/W |
| Operating and Storage Temperature Range                              | TJ, TSTG         | -55 to | +175 | С°   |

# Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic                     | Symbol | Min | Тур | Max  | Unit | Test Condition                                |
|------------------------------------|--------|-----|-----|------|------|---|
| Reverse Breakdown Voltage (Note 7) | V(BR)R | 150 | _   | _    | V    | $I_R = 2\mu A$                                |
| Forward Voltage                    | VF     | —   | _   | 0.82 | V    | I <sub>F</sub> = 1.0A                         |
| Leakage Current (Note 7)           | IR     | —   | _   | 2    | μA   | V <sub>R</sub> = 150V, T <sub>A</sub> = +25°C |
| Total Capacitance                  | Ст     | _   | 28  | _    | pF   | V <sub>R</sub> = 5V <sub>DC</sub> , f = 1MHz  |

5. Theoretical  $R_{\theta JS}$  calculated from the top center of the die straight down to the PCB/cathode tab solder junction.

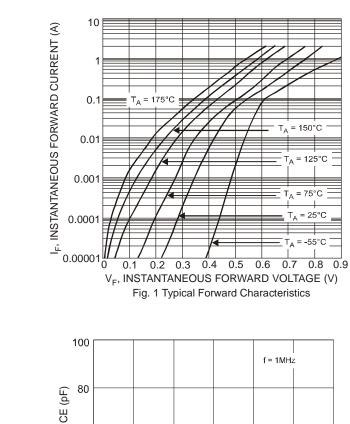
E. Theoretical Page calculated from the top center of the die straight down to the POD/callide tab solder junction.
Part mounted on FR-4 board with 2 oz., minimum recommended copper pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.
Obset download to the page outlines.html.

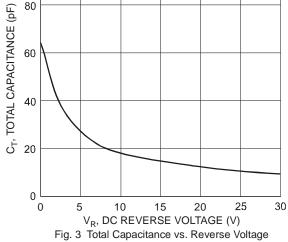
Notes:

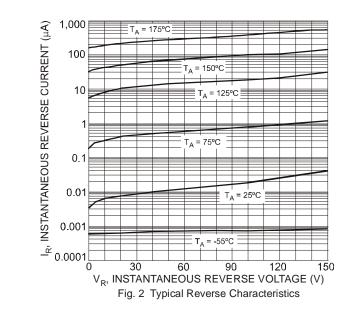
7. Short duration pulse test used to minimize self-heating effect.



# **DFLS1150**



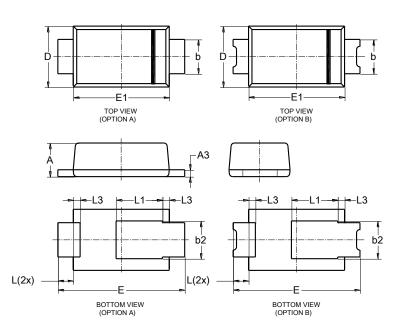






### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

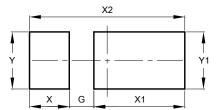


|       | PowerDI123           |       |      |  |  |  |  |
|-------|----------------------|-------|------|--|--|--|--|
| Dim   | Min                  | Max   | Тур  |  |  |  |  |
| Α     | 0.93                 | 1.00  | 0.98 |  |  |  |  |
| A3    | 0.15                 | 0.25  | 0.20 |  |  |  |  |
| b     | 0.85                 | 1.25  | 1.00 |  |  |  |  |
| b2    | 1.025                | 1.125 | 1.10 |  |  |  |  |
| D     | 1.63                 | 1.93  | 1.78 |  |  |  |  |
| Е     | 3.50                 | 3.90  | 3.70 |  |  |  |  |
| E1    | 2.60                 | 3.00  | 2.80 |  |  |  |  |
| L     | 0.40                 | 0.50  | 0.45 |  |  |  |  |
| L1    | 1.25                 | 1.40  | 1.35 |  |  |  |  |
| L3    | 0.125                | 0.275 | 0.20 |  |  |  |  |
| All I | All Dimensions in mm |       |      |  |  |  |  |

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI123



| Dimensions | Value   |  |  |
|------------|---------|--|--|
| Dimensions | (in mm) |  |  |
| G          | 0.65    |  |  |
| Х          | 1.05    |  |  |
| X1         | 2.40    |  |  |
| X2         | 4.10    |  |  |
| Y          | 1.50    |  |  |
| Y1         | 1.50    |  |  |

#### PowerDI123



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